



US00D436357S

(12) **United States Design Patent**
Klinker

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(54) **PROCESSOR PACKAGE**

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(**) Term: **14 Years**

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(51) **LOC (7) Cl.** **14-02**

(52) **U.S. Cl.** **D14/432**

(58) **Field of Search** D14/114, 117,
D14/121; D13/156; D8/353; 242/348, 348.4,
341, 342-5, 345.1, 346, 345.3, 346.2; 273/148 R;
361/737, 752; D21/324-33; 257/678-9

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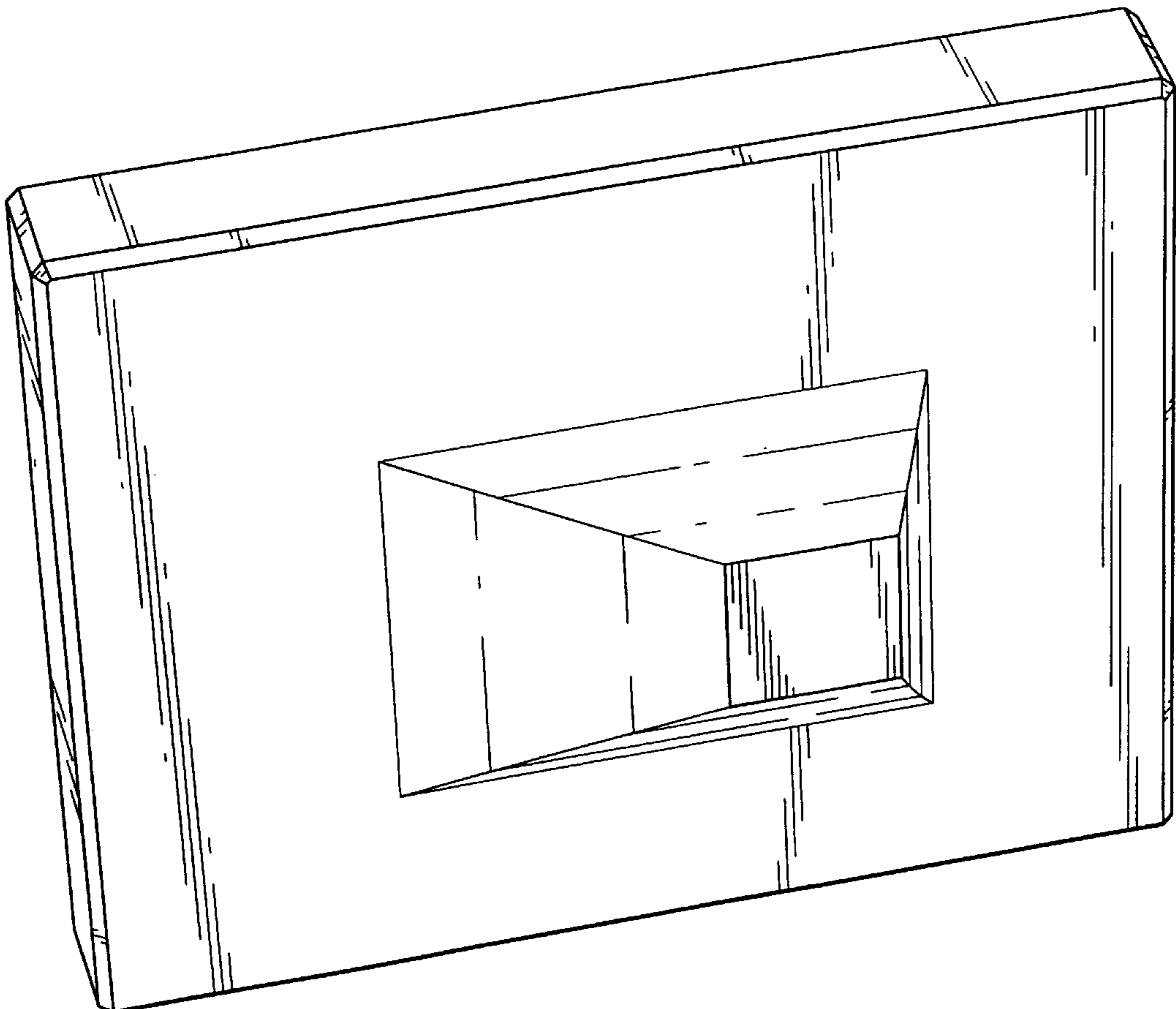
(57) **CLAIM**

The ornamental design for a processor package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a processor package including an indented area on a surface.
 FIG. 2 is a front view of the processor package.
 FIG. 3 is a top view of the processor package.
 FIG. 4 is a back view of the processor package.
 FIG. 5 is a right side view of the processor package.
 FIG. 6 is a left side view of the processor package.
 FIG. 7 is a bottom view of the processor package; and,
 FIG. 8 is a cross-sectional view of the processor package taken along line 8—8 in FIG. 2.

1 Claim, 4 Drawing Sheets



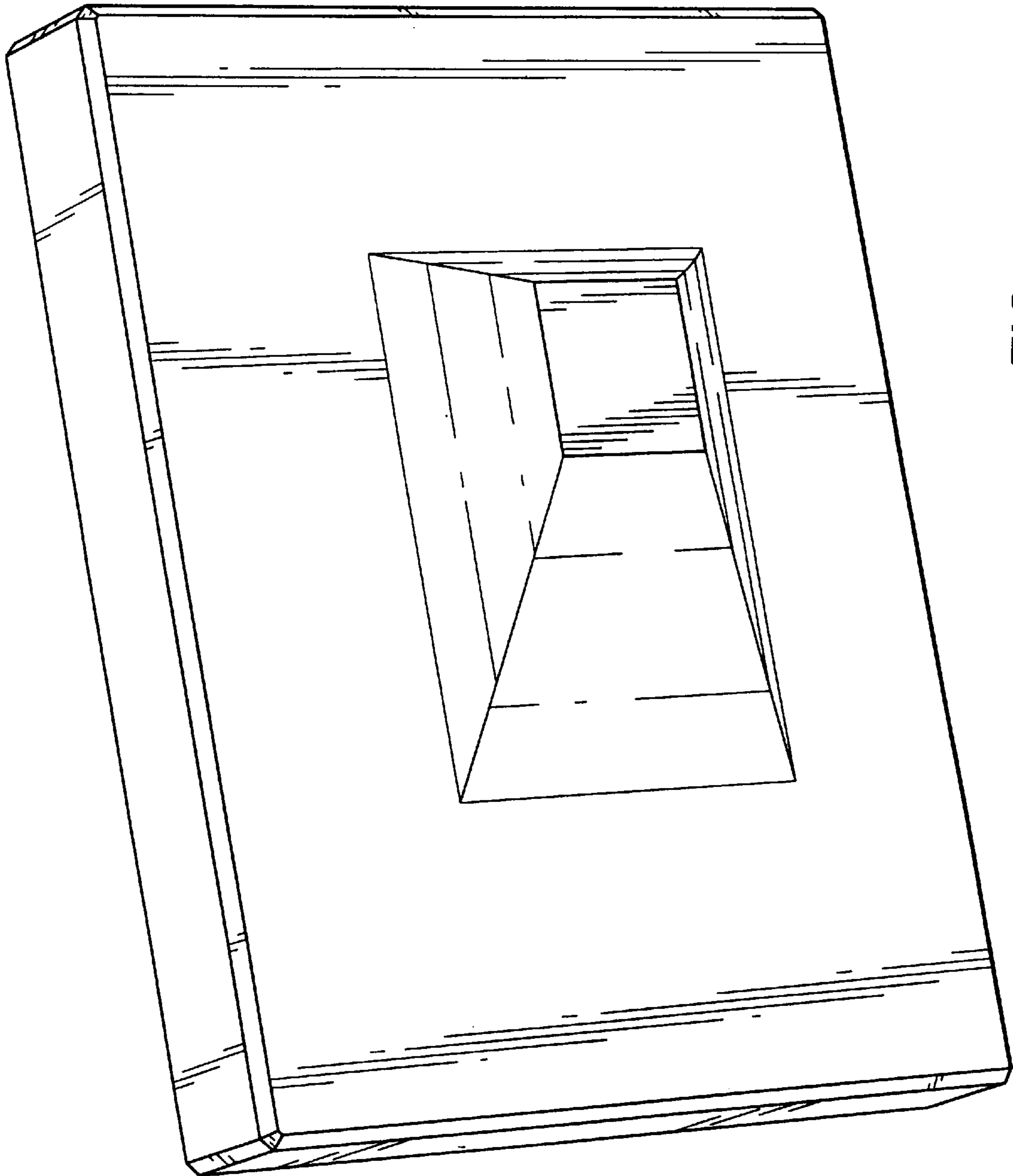


FIG. 1

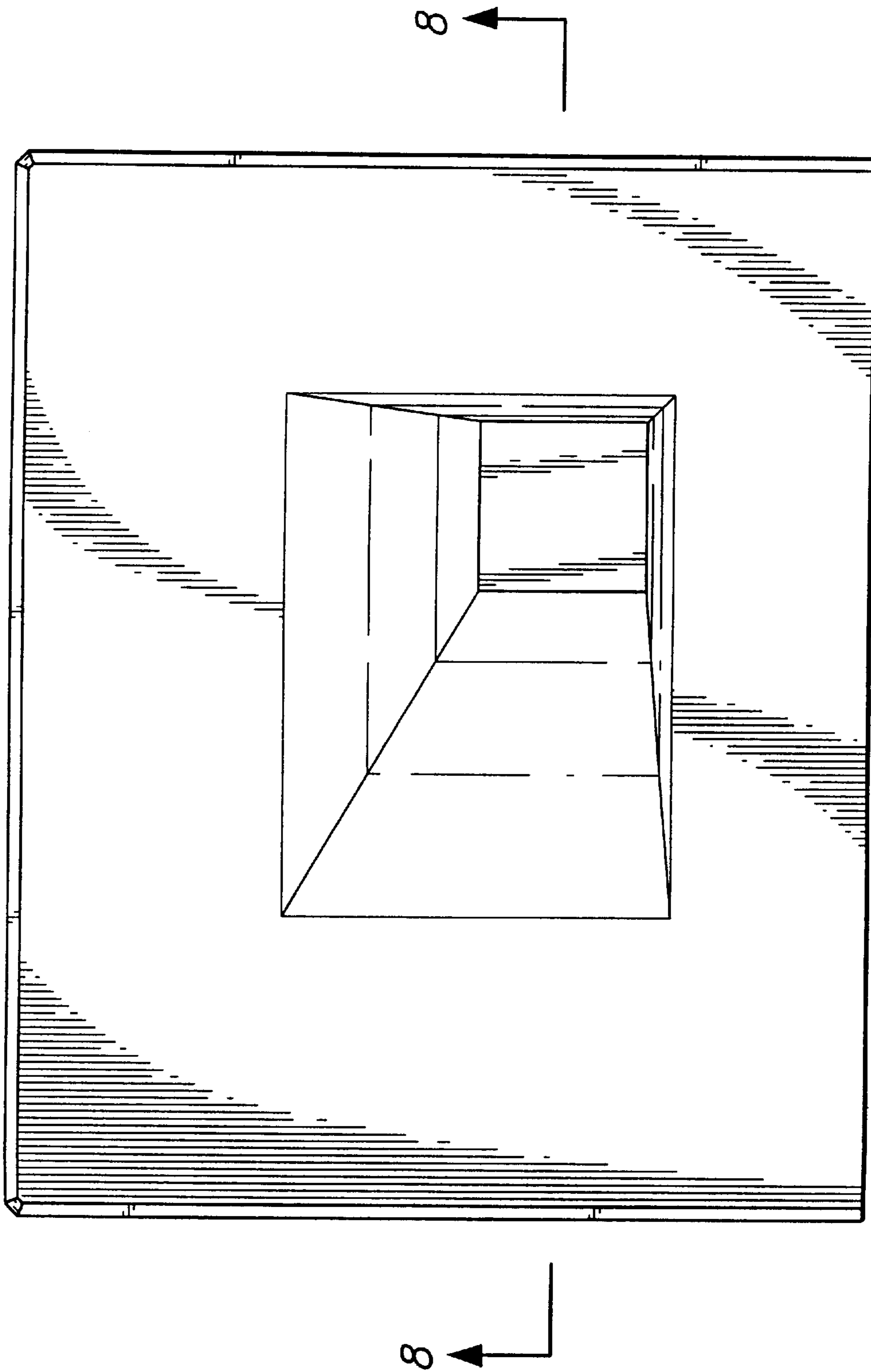


FIG. 2

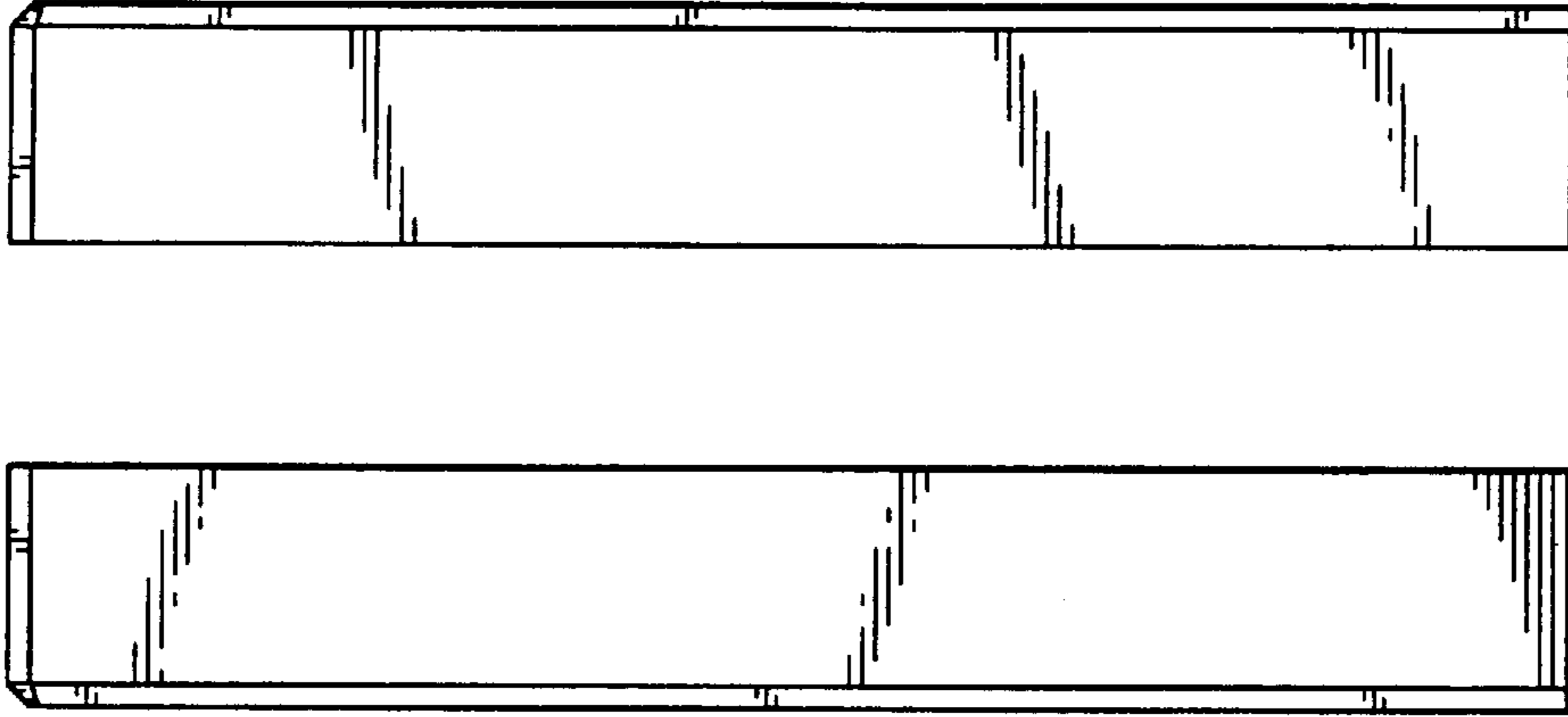


FIG. 5
FIG. 6

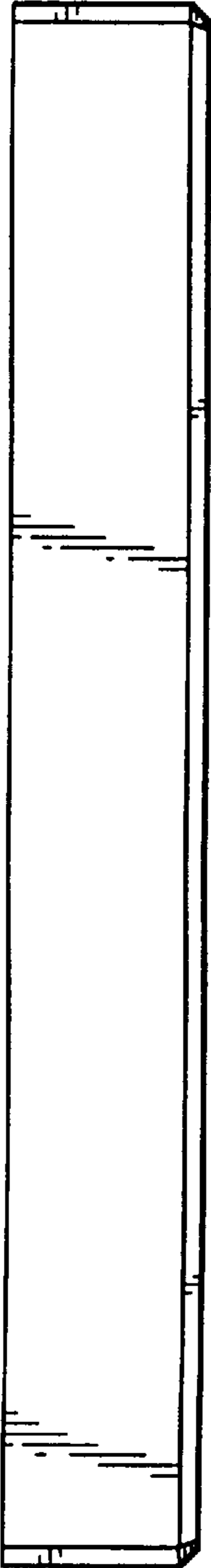


FIG. 3

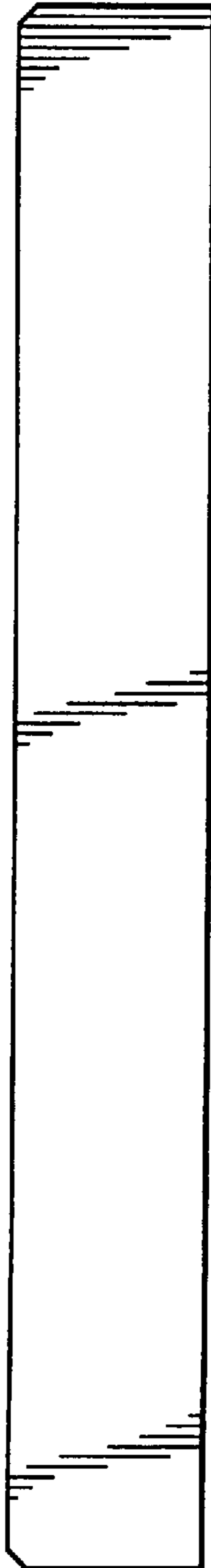


FIG. 7

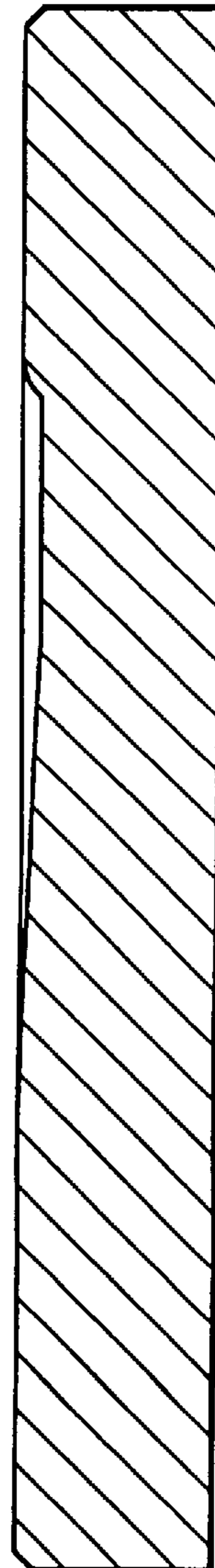


FIG. 8

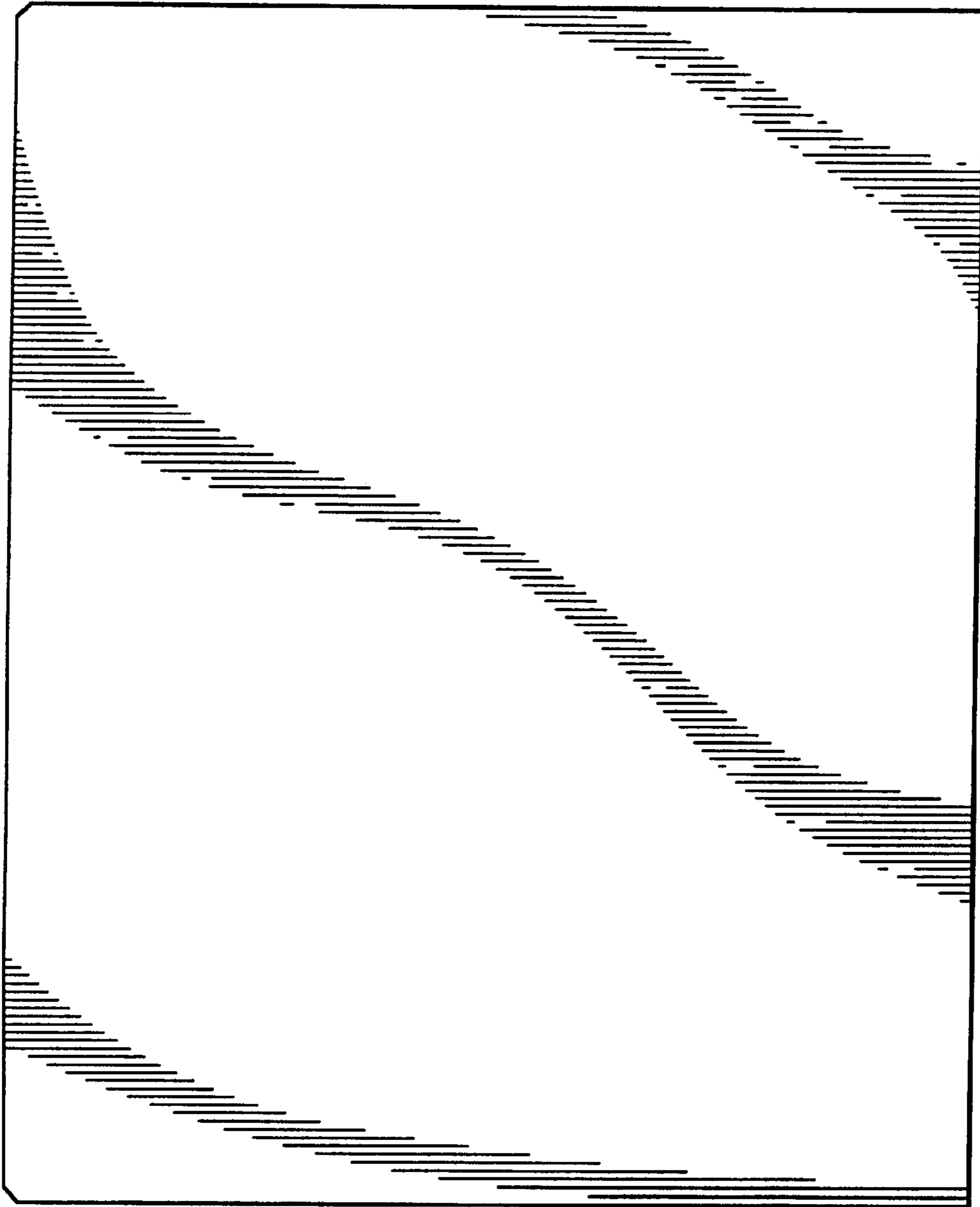


FIG. 4